



CS280 - 63/37 Sn/Pb SOLDER BALLS
 CSG280 - Sn/Ag/Cu SOLDER BALLS

SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	\approx	\approx	1.20
A ₁	0.20	\approx	\approx
A ₂	0.55	\approx	\approx
D/E	16.00 BSC		
D ₁ /E ₁	14.40 BSC		
e	0.80 BSC		
ø _b	0.35	0.40	0.45
bbb	\approx	\approx	0.10
ccc	\approx	\approx	0.12
ddd	\approx	\approx	0.15
eee	\approx	\approx	0.08
M	19		

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE.
3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
4. CONFORMS TO JEDEC MO-216-BAL-1 (DEPOPULATED).

280-BALL LAMINATE CHIP SCALE BGA, 0.80MM PITCH (CS280/CSG280)